



## FEATURES

The RS1AF~RS1MF are available in SMAF Package

- Glass Passivated Chip Junction
- Fast Recovery Time for High Efficiency
- Surge Overload Rating to 25A Peak
- Ideally Suited for Automated Assembly

## MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00086oz

## ORDERING INFORMATION

Package Type	Part Number
SMAF	RS1AF
	RS1BF
	RS1DF
	RS1GF
	RS1JF
	RS1KF
	RS1MF
SPQ	3,000pcs/Reel
AiT provides all RoHS Compliant Products	

## PIN DESCRIPTION



SMAF



1 Cathode  
2 Anode



**ABSOLUTE MAXIMUM RATINGS**

T<sub>A</sub> = 25°C, unless otherwise specified.

Parameter	Symbols	RS1AF	RS1BF	RS1DF	RS1GF	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	V
Maximum Average Forward Rectified Current at T <sub>A</sub> = 65 °C	I <sub>F(AV)</sub>	1				A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	25				A
Maximum Instantaneous Forward Voltage at 1 A	V <sub>F</sub>	1.3				V
Maximum DC Reverse Current T <sub>A</sub> = 25 °C at Rated DC Blocking Voltage T <sub>A</sub> =125 °C	I <sub>R</sub>	5				μA
		100				
Maximum Reverse Recovery Time*	t <sub>rr</sub>	150				ns
Typical Junction Capacitance **	C <sub>j</sub>	15				pF
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150				°C
Parameter	Symbols	RS1JF	RS1KF	RS1MF	Units	
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600	800	1000	V	
Maximum RMS voltage	V <sub>RMS</sub>	420	560	700	V	
Maximum DC Blocking Voltage	V <sub>DC</sub>	600	800	1000	V	
Maximum Average Forward Rectified Current at T <sub>A</sub> = 65 °C	I <sub>F(AV)</sub>	1				A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	25				A
Maximum Instantaneous Forward Voltage at 1 A	V <sub>F</sub>	1.3				V
Maximum DC Reverse Current T <sub>A</sub> = 25 °C at Rated DC Blocking Voltage T <sub>A</sub> =125 °C	I <sub>R</sub>	5				μA
		100				
Maximum Reverse Recovery Time*	t <sub>rr</sub>	250	500		ns	
Typical Junction Capacitance**	C <sub>j</sub>	15				pF
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150				°C

\* Measured with I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1 A, I<sub>rr</sub> = 0.25 A

\*\* Measured at 1MHz and applied reverse voltage of 4V D.C.

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



### TYPICAL CHARACTERISTICS

Fig 1. Forward Current Derating Curve

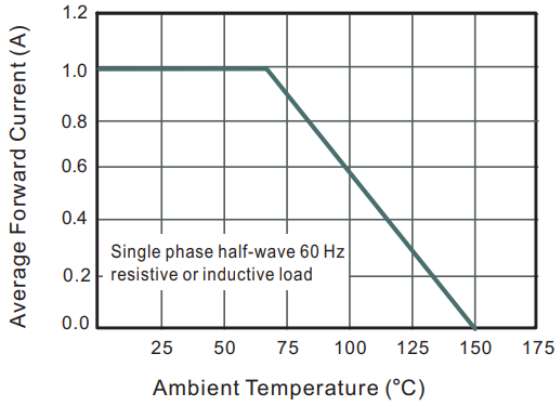


Fig 2. Typical Reverse Characteristics

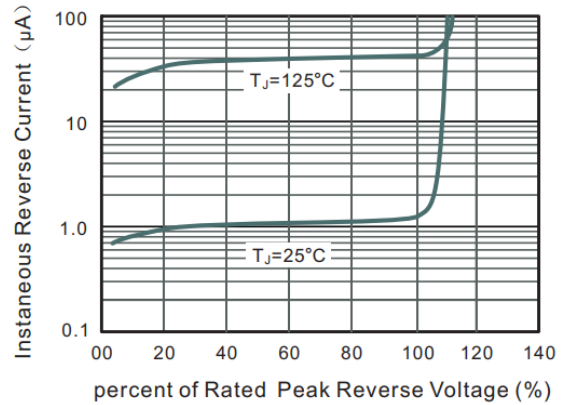


Fig 3. Typical Instantaneous Forward Characteristics

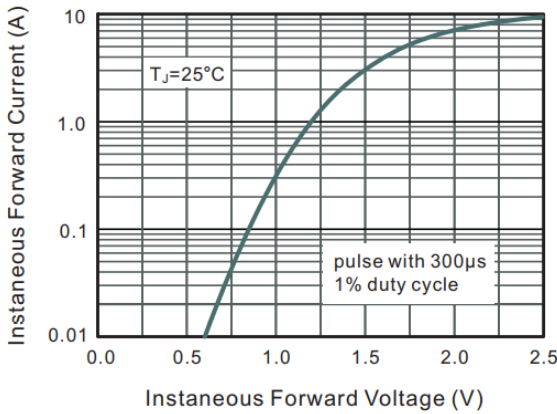


Fig 4. Typical Junction Capacitance

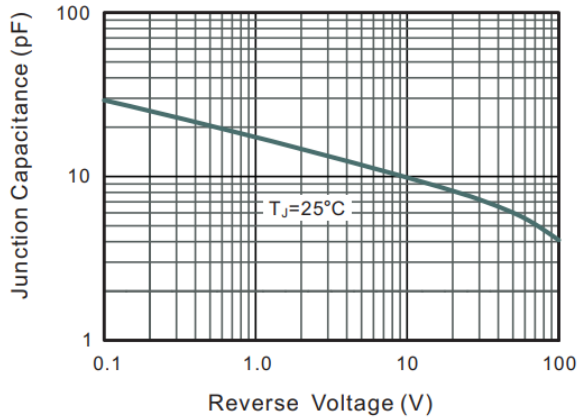
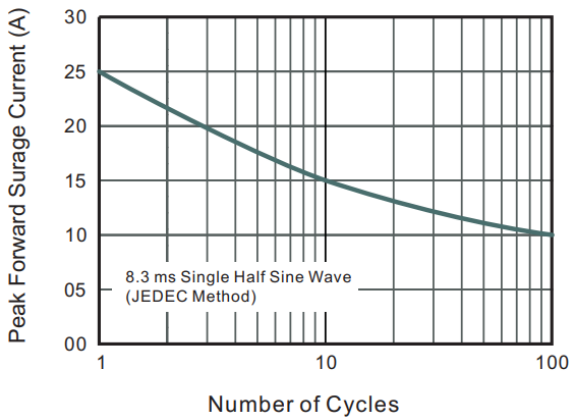


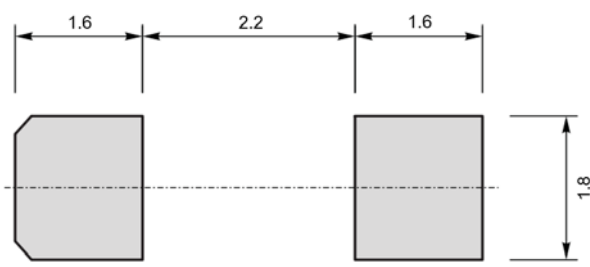
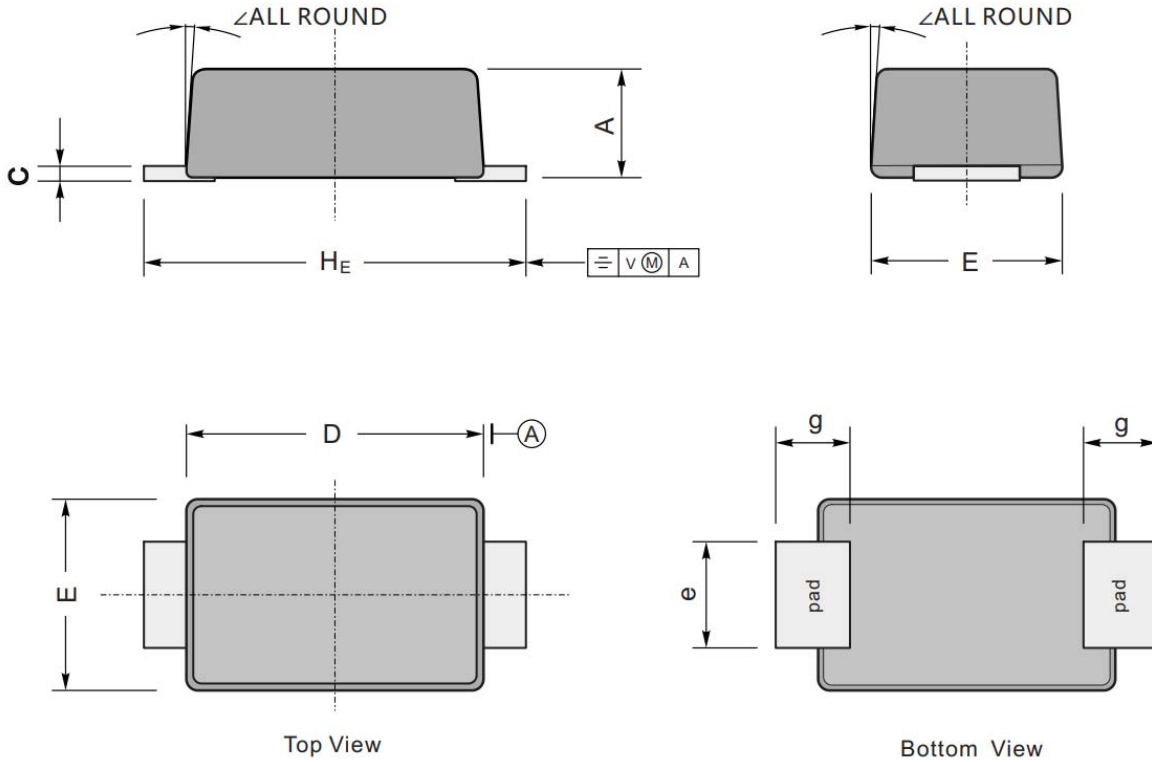
Fig 5. Maximum Non-Repetitive Peak Forward Surge Current





**PACKAGE INFORMATION**

Dimension in SMAF (Unit: mm)



RECOMMENDED LAND PATTERN

Symbol	Min	Max
A	0.9	1.1
C	0.12	0.20
D	3.3	3.7
E	2.4	2.7
e	1.3	1.6
g	0.8	1.2
$H_E$	4.4	4.9
$\angle$	7°	



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